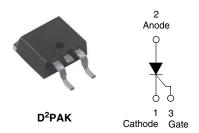


Vishay Semiconductors

Surface Mountable Phase Control SCR, 16 A



PRODUCT SUMMARY			
V _T at 10 A	< 1.4 V		
I _{TSM}	200 A		
V _{RRM}	1600 V		

FEATURES

 Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C



• Compliant to RoHS directive 2002/95/EC

• Designed and qualified for industrial level

APPLICATIONS

- Input rectification (soft start)
- Vishay input diodes, switches and output rectifiers which are in identical package outlines

DESCRIPTION

The VS-16TTS16SPbF High Voltage Series of silicon controlled rectifiers are specifically designed for medium power switching and phase control applications. The glass passivation technology used has reliable operation up to 125 °C junction temperature.

OUTPUT CURRENT IN TYPICAL APPLICATIONS					
APPLICATIONS SINGLE-PHASE BRIDGE THREE-PHASE BRIDGE UNITS					
NEMA FR-4 or G-10 glass fabric-based epoxy with 4 oz. (140 µm) copper	2.5	3.5			
Aluminum IMS, R _{thCA} = 15 °C/W	6.3	9.5	A		
Aluminum IMS with heatsink, R _{thCA} = 5 °C/W	14.0	18.5			

Note

• $T_A = 55$ °C, $T_J = 125$ °C, footprint 300 mm²

MAJOR RATINGS AND CHARACTERISTICS					
SYMBOL	CHARACTERISTICS	VALUES	UNITS		
I _{T(AV)}	Sinusoidal waveform	10	۸		
I _{RMS}		16	A		
V _{RRM} /V _{DRM}		1600			
I _{TSM}		200	A		
V _T	10 A, T _J = 25 °C	1.4	V		
dV/dt		500	V/µs		
dl/dt		150	A/µs		
T _J		- 40 to 125	°C		

VOLTAGE RATINGS					
PART NUMBER	V _{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V _{DRM} , MAXIMUM PEAK DIRECT VOLTAGE V	I _{RRM} /I _{DRM} AT 125 °C mA		
VS-16TTS16SPbF	1600	1600	10		

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ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	
PANAIVIETEN	STINIBUL			MAX.	UNITS
Maximum average on-state current	I _{T(AV)}	T _C = 93 °C, 180° conduction, half sine wave	1	0	
Maximum RMS on-state current	I _{RMS}		1	6	_
Maximum peak, one-cycle,	I	10 ms sine pulse, rated V _{RRM} applied	1	70	- A
non-repetitive surge current	I _{TSM}	10 ms sine pulse, no voltage reapplied	2	00	
Maximum I ² t for fusing	l ² t	10 ms sine pulse, rated V _{RRM} applied		14	A ² s
Maximum i-t for fusing	Ι - τ	10 ms sine pulse, no voltage reapplied		200	
Maximum I ² √t for fusing	I²√t	t = 0.1 ms to 10 ms, no voltage reapplied		00	A²√s
Maximum on-state voltage drop	V_{TM}	10 A, T _J = 25 °C		.4	V
On-state slope resistance	r _t	T _J = 125 °C		1.0	mΩ
Threshold voltage	V _{T(TO)}			.1	V
Maximum reverse and direct leakage current	1 /1	$T_J = 25 ^{\circ}\text{C}$	0	.5	
waximum reverse and direct leakage current	I _{RM} /I _{DM}	$V_R = Rated V_{RRM}/V_{DRM}$	1	0	mA
Holding current	I _H	Anode supply = 6 V, resistive load, initial I _T = 1 A 100		150	IIIA
Maximum latching current	ΙL	Anode supply = 6 V, resistive load 200		00	
Maximum rate of rise of off-state voltage	dV/dt		5	00	V/µs
Maximum rate of rise of turned-on current	dl/dt		1:	50	A/µs

TRIGGERING					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum peak gate power	P _{GM}		8.0	10/	
Maximum average gate power	P _{G(AV)}		2.0	W	
Maximum peak positive gate current	+ I _{GM}		1.5	Α	
Maximum peak negative gate voltage	- V _{GM}		10	V	
Maximum required DC gate current to trigger	lgт	Anode supply = 6 V, resistive load, T _J = - 10 °C	90	mA	
		Anode supply = 6 V, resistive load, T _J = 25 °C	60		
		Anode supply = 6 V, resistive load, T _J = 125 °C	35		
Maximum required DC gate voltage to trigger	V _{GT}	Anode supply = 6 V, resistive load, T _J = - 10 °C	3.0	V	
		Anode supply = 6 V, resistive load, T _J = 25 °C	2.0		
		Anode supply = 6 V, resistive load, T _J = 125 °C	1.0		
Maximum DC gate voltage not to trigger	V_{GD}	T 105 °C V Detect value	0.25		
Maximum DC gate current not to trigger	I_{GD}	$T_J = 125 ^{\circ}\text{C}, V_{DRM} = \text{Rated value}$ 2.0		mA	

SWITCHING				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Typical turn-on time	t _{gt}	T _J = 25 °C	0.9	
Typical reverse recovery time	t _{rr}	T. – 195 °C	4	μs
Typical turn-off time	t _q	T _J = 125 °C	110	

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THERMAL - MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		- 40 to 125	°C
Soldering temperature	T _S	For 10 s (1.6 mm from case) 240		
Maximum thermal resistance, junction to case	R _{thJC}	DC operation	1.3	°C/W
Typical thermal resistance, junction to ambient	R _{thJA}	PCB mount ⁽¹⁾ 40		G/W
Approximate weight			2	g
Approximate weight			0.07	OZ.
Marking device		Case style D ² PAK (SMD-220)	16TTS	16S

Note

⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μm) copper 40 °C/W. For recommended footprint and soldering techniques refer to application note #AN-994.

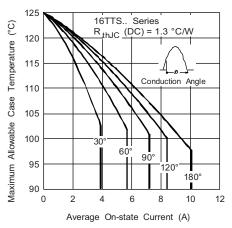


Fig. 1 - Current Rating Characteristics

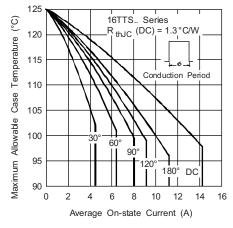


Fig. 2 - Current Rating Characteristics

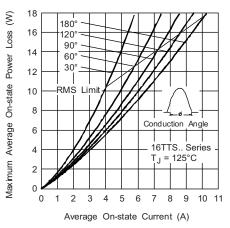


Fig. 3 - On-State Power Loss Characteristics

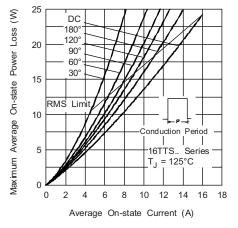


Fig. 4 - On-State Power Loss Characteristics

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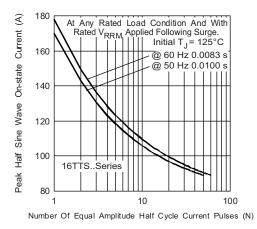


Fig. 5 - Maximum Non-Repetitive Surge Current

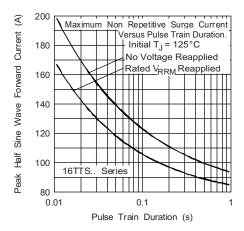


Fig. 6 - Maximum Non-Repetitive Surge Current

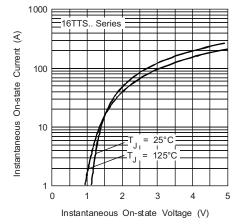


Fig. 7 - On-State Voltage Drop Characteristics

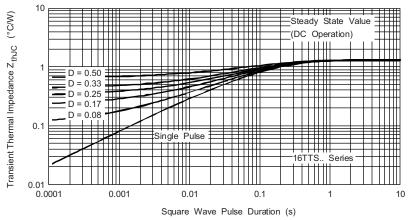


Fig. 8 - Thermal Impedance Z_{thJC} Characteristics

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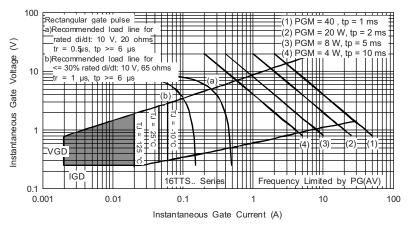
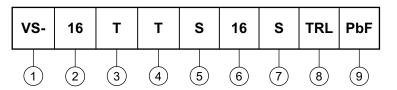


Fig. 9 - Gate Characteristics

ORDERING INFORMATION TABLE

Device code



- 1 HPP product suffix
- 2 Current rating
- 3 Circuit configuration:
 - T = Single thyristor
- 4 Package:
 - T = TO-220AC
- 5 Type of silicon:
 - S = Standard recovery rectifier
- 6 Voltage rating: Voltage code x 100 = V_{RRM} (16 = 1600 V)
- **7** S = TO-220 D²PAK (SMD-220) version
- 8 • None = Tube
 - TRL = Tape and reel (left oriented)
 - TRR = Tape and reel (right oriented)
- 9 PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS				
Dimensions <u>www.vishay.com/doc?95046</u>				
Part marking information	www.vishay.com/doc?95054			
Packaging information	www.vishay.com/doc?95032			



Vishay

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